

Highly density GPU server
based on Intel Xeon Scalable 3rd generation



No contractual

Isometric view



No contractual

Front view

Key Features



19-inch - 1U/4 GPUs



Dual Intel® Xeon®
3rd Gen socket



32x DDR4 @ 3200MHz



4x PCIe 4.0 x16 for GPU/FPGAs
2x PCIe 4.0 x16 LP
1x OCP 3.0 x16



Air Cooling

3rd Gen Intel® Xeon® Scalable Processors

The Godí 1.4iP is built with the latest Intel® Xeon® Scalable Processors, and designed for the demand of high scalability, high density computing, and widest range of workloads. 3rd Gen Intel® Xeon® Scalable processors offer a balanced architecture with built-in acceleration and advanced security capabilities.

Cloud and Enterprise Made Flexible

The latest 3rd Gen Intel® Xeon® Scalable processors are built upon years of cloud innovation, tuned to your unique needs with built-in AI and Intel® Crypto Acceleration and advanced security capabilities.

The acceleration at its best with NVIDIA & AMD GPUs or FPGAs

From 3D modeling, CAD and amazing visualisation renders, to the most demanding AI training and Inference workloads, the Godí 1.4iP enables any of NVIDIA's latest Tesla, Quadro and AMD Mi GPU series to be used at its best performances.

Need to decode many audio and video feeds ? The Godí 1.4iP can also carry multiple FPGAs, allowing a single system to run an entire infrastructure.

The acceleration at its best with NVIDIA & AMD GPUs or FPGAs

With all acceleration cards in front IO, in addition to better cooling capabilities, the IO is now accessible in the front.

From High density network to direct access to FPGAs or video outputs, the Godí 1.4iP is the only server on the market designed to be deployed as much on single entity mode as in data center environment.



SCAN THE CODE!

TO DISCOVER MORE
ABOUT THIS PRODUCT

SPECIFICATIONS

System	Model	BRB-GI1-104iP-R010
	Form factor	1U
	Nodes	1
	Dimension	482mm (W) x 900mm (D) x 44mm (H) 19" (W) x 35,43" (D) x 1.73" (H)
	Cooling Technology	Air Cooling
Storage	Internal type	1x M.2 NVMe PCIe3.0 x4 support 2280/2260/2242
	External type	None
	RAID Controller	None
Motherboard	CPU	2x Socket P+ (LGA 4189) Intel® XEON® 3rd Generation Scalable Processors family TDP 270W maximum/CPU
	Chipset	Intel C621A
	Expansion slots	4x PCIe4.0 x16 slots for FHFL GPU/FPGA form factor TDP up to 250W/Card 2x PCIe4.0 x16 slot 1x OCP 3.0 PCIe4.0 x16 slot
	BMC	Integrated Aspeed® AST2500
	TPM	1x (13-pin,SPI)
Memory	Total slots	32 (8-channel per CPU)
	Capacity	Maximum up to 4TB per Node ((Using RDIMM 3DS 128GB)
	Memory type	DDR4 2933/3200 RDIMM up to 128GB DDR4 2933/3200 LR-DIMM 3DS up to 128GB
Network		1x 1GbE Management Port dedicated to the IPMI
I/O	Rear	1x VGA Port (DB15) 1x Dedicated IPMI 1x DB9 2x USB 3.2 1x UID 1x PWR BTN
Management Solution	Software	AMI MegaRAC
	Out of band remote management	WebGUI, Intelligent Platform Management Interface (IPMI)
Power Supply	Type	1+1 Redundant CRPS
	Power rating	1600W 180–240Vac
	Power Efficiency	80 PLUS Platinum (94%)
Operating Environment	Operating Temperature	Operation temperature: 10°C ~ 35°C (50°F ~ 95°F)
	Non-operating Temperature	Non operation temperature: -40°C ~ 60°C (40° ~ 140°F)
	Operating Relative Humidity	Up to 90%
	Non-operating Relative Humidity:	95%, non-condensing at 35° C
Warranty	2CRSi hardware warranty includes a one year, parts and labour with return to 2CRSi selling entity. Customers may purchase an extended warranty of up to 3 years on parts and labour with different support levels. Please contact 2CRSi at support@2crsi.com or reach your sales point of contact for complete warranty details including limitations and transferability. 2crsi.com/global-location	